

■ Wafer Marking System



Small footprint.

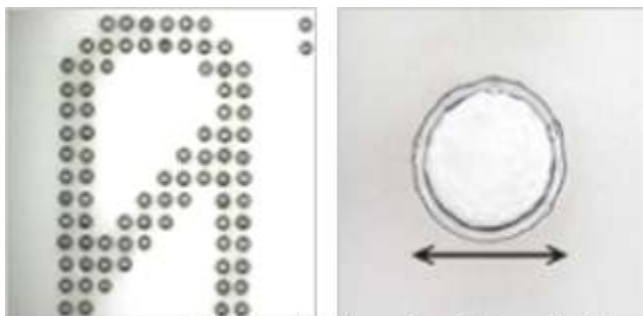
Features

This system is for marking on wafers; silicon wafer, sapphire substrate, and compound wafer.

- Small footprint.
- Highly precise marking.
- High throughput.

[White marking: by SHG laser]

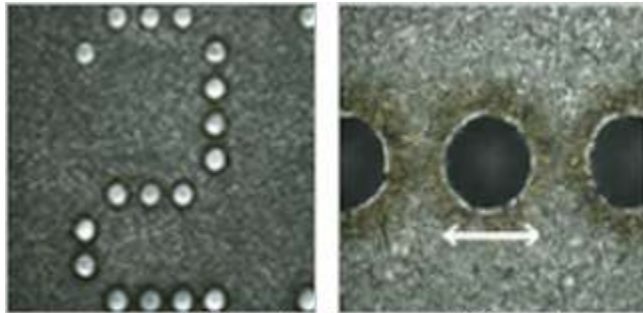
It melts only surface of a silicon wafer, so marking can be done without particles.



Φ70μm in diameter, 2.5μm in deep

[Black marking: by fundamental laser]

It engraves surface of a silicon wafer. Marked workpiece has a high level of visibility and can be read clearly even after cleansing and grinding.



Φ60μm in diameter, 100μm in deep



Inside of the system



Control display

Specifications

Wafer size	4, 5, 6, 8 inch, and 12 inch*
Marking	Soft / hard marking
Marking positioning accuracy	+/- 200µm (Option: +/- 75µm)
Takt time	150WPH (5x9 dots, 12 letters)

*For 12 inch (Two cassettes FOUP)